

ABSTRACT

An information processing apparatus (5) includes: an information acquisition section (500) configured to acquire polishing condition information including top-ring vibration information indicating vibration of a top ring in chemical mechanical polishing of the substrate and top-ring sound information indicating sound generated from the top ring in the chemical mechanical polishing of the substrate performed by a substrate processing apparatus including a polishing table rotatably supporting the polishing pad and the top ring configured to press the substrate against the polishing pad; and a state prediction section (501) configured to predict substrate slip-out information for the polishing condition information by inputting the polishing condition information acquired by the information acquisition section (500) to a learning model (10A) that has been generated by machine learning that causes the learning model to learn a correlation between the polishing condition information and the substrate slip-out information indicating occurrence of slip out of the substrate on which the chemical mechanical polishing is performed.

FIG. 13